AMENDMENT

IN THE CLAIMS:

Please amend the claims as follows:

1-17. (Canceled)

18. (Currently amended) A substrate processing method comprising:

providing a substrate having a lower layer having low wettability and an upper layer having high wettability arranged on the lower layer;

simultaneously supplying a chemical liquid and a rinse liquid onto the substrate, while moving a chemical-liquid supplying position on a surface of the substrate to which the chemical liquid is supplied from a periphery of the substrate toward a center of the substrate, and moving a rinse-liquid supplying position on the surface of the substrate to which the rinse liquid is supplied in such a manner that the rinse-liquid supplying position is located radially outside the chemical-liquid supplying position and follows the chemical-liquid supplying position, a relative positional relationship between the chemical-liquid supplying position and the rinse-liquid supplying position being essentially constant, whereby an area covered with a chemical liquid film of the chemical liquid and moving toward the center of the substrate is formed on the surface of the substrate between the chemical-liquid supplying position and the rinse-liquid supplying position, and the rinse liquid is supplied onto the chemical liquid film to form an area covered with a mixed liquid film of an mixture of the chemical liquid and the rinse liquid on the substrate radially outside the rinse-liquid supplying position, so that any portion of the surface of the substrate is primarily covered with the chemical liquid film for a period of time from a point of time at which the-chemical liquid supplying position reaches the portion to a point of time at which the rinse-liquid supplying position reaches the portion, and then covered with the mixed liquid film from a point of time at which the rinse-liquid supplying position reaches the portion,

wherein the period of time is determined so that the ~~hydrophilic film~~ upper layer existing in the portion is partially removed by the chemical liquid to partially expose the underlying lower layer while partially remaining the upper layer in the portion non-removed during the period of time.

19. (Previously presented) A method according to claim 18, wherein the period of time is determined beforehand by conducting an experiment by which a time necessary for removing the upper layer to expose the lower layer is measured.

20. (Currently amended) A method according to claim 18, wherein the chemical liquid comprises hydrofluoric acid, and the ~~hydrophilic film~~ upper layer is a silicon oxide film.

21. (Previously presented) A method according to claim 18, wherein the supplying of the chemical liquid is stopped when the chemical-liquid supplying position reaches the center of the substrate.

22. (Previously presented) A method according to claim 21, wherein the supplying of the rinse liquid is continued after stopping supplying the chemical-liquid, and the rinse-liquid supplying position is moved to the center of the substrate.

23. (Previously presented) A method according to claim 22, wherein a rinse-liquid supplying rate is increased after the rinse-liquid supplying position is moved to the center of the substrate.

24-29. (Canceled)